# Electronics for Extreme Environments Conference (incorporating HiTEN)

30<sup>th</sup> June – 1<sup>st</sup> July 2026

"Electronics That Must Endure"

**CALL FOR ABSTRACTS** 

Abstract Deadline: 30<sup>th</sup> January 2026



### Venue: Churchill College, Cambridge, UK

#### 5 reasons to attend the Electronics for Extreme Environments Conference:

- How to bring electronics into harsh environments to solve your problems
- Understand how to validate components for extreme environments
- Learn about materials, components and devices for harsh environments
- Network and learn from other applications, industries and specialities
- Participate in extending the capabilities of sensing, IoT and AI to new environments

IMAPS-UK invites you to submit an abstract (200-300 words) by Friday 30<sup>th</sup> January 2026 covering any of the topics below to mailto:office@imaps.org.uk:

#### **Electronics for Extreme Environments Conference Topics High and Low Severe Mechanical High Field Strength Ultra Long Life Electronics** and Environmental **Temperature Conditions Applications** Mechanical Shock **Automotive** Radiation Long Term Storage Tolerant and and Vibration **Power Budgets** Aerospace/Space Rad-Hard Chemical: Defence/Security Charging/Discharging **EMC Emissions** Humidity **Energy** and **Remote Sensing** and Susceptibility Corrosion Renewables Structural embedded Magnetic Fields Data Centres/AI **Explosive** electronics High Voltage Medical Atmospheres **Autonomous Systems Photonics Medical Implants** Testing and Reliability High and Low Pressure **Quantum Computing** Cryogenic Test and Reliability

#### **Example Applications Areas:**

- Reducing consumption in energy intensive processes.
- Safety in hostile industrial environments
- Sensing in extreme environments
- Providing security on critical defence applications

The Electronics for Extreme Environments 2026 Conference focuses on "Electronics That Must Endure". This in-person Conference combines invited Keynotes, Presentations and Posters from leading Industrial Companies, Academics and Research Institutions developing sensors, semiconductors, components, energy sources, packaging and assemblies that must perform reliably under extreme conditions, including high and low temperatures, high field strengths, severe mechanical and environmental conditions and ultra-long life electronics. This Conference follows on from and extends the High Temperature Electronics Network (HITEN).

#### **Instructions for Abstract Submission**

**Research and Development Papers and Posters:** These will describe high-impact academic research relating to the conference topics.

**Technical Presentations:** Technical presentations showcasing in-production or pre-production techniques relating to the conference topics.

**Current/Future trends:** Presentations demonstrating how markets related to the main conference topics are developing over time.

All abstracts received by the submission deadline will be evaluated by the Technical Committee. Abstracts covering a balanced range of the main conference topics will be selected and invited to provide an **Oral Presentation** during the conference and others will be selected for **Poster Presentation** in the Exhibition Area for the Conference.

## **Awards** available for selected **Posters** submitted and presented by **Students and Early Career Professionals**

Those wishing to present their work at the Electronics for Extreme Environments Conference 2026 should submit an abstract of 200-300 words, electronically to: office@imaps.org.uk by Friday 30<sup>th</sup> January 2026.

Deadlines	
Abstract submission (200-300 words)	Friday 30 <sup>th</sup> January 2026
Acceptance of Abstracts for Oral and Poster Presentation	Friday 27 <sup>th</sup> February 2026
Confirmed speaker abstracts and biographies	Friday 29 <sup>th</sup> May 2026
Final presentations prepared	Friday 26 <sup>th</sup> June 2026

